

ATM-1100K

Full-Automatic DFR Film Laminator

Outline

ATM-1100K is the ideal system for laminating DFR and B/G tape on wafers and its uniform lamination capability is the highest level in the market. (comparison by Takatori)

Features

- Lamination pressure on and the temperature of whole wafer surface are uniformed.
- DFR lamination roller temperature is precisely controlled
- DFR lamination tension is uniformed (Non-tension lamination and tenting lamination are available.)
- Corresponding to protective tape lamination for back-grind process
- Environment friendly design (long life consumable parts, minimizing film consumption etc.)
- Improved workability



Specification		ATM-1100K
Throughput		Approx. 50 wafers per hour (8" wafer, varies according to the processing conditions)
Wafer Size		4, 5, 6 and 8 inch
Tape Width		130mm ∼ 230mm
Utilities	Power	AC200V Single phase 50/60Hz 4.0 KVA
	Air	Pressure 0.4 ~ 0.5Mpa 90Nl/min
	Vacuum sourse	—74Kpa
Dimensions		D 1,340 \times W 1,030 \times H 1,750 mm (signal tower light not included)
Weight		700 kg

Specifications are subject to change without prior notice from the supplier.

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